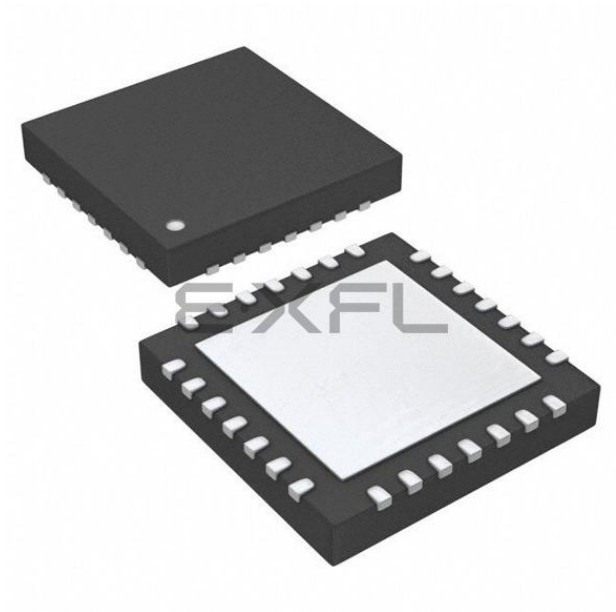

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What is "Embedded - Microcontrollers"?

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf25k22-e-ml

Table of Contents

1.0 DEVICE OVERVIEW

This document contains device specific information for the following devices:

- PIC18F23K22
- PIC18F24K22
- PIC18F25K22
- PIC18F26K22
- PIC18F43K22
- PIC18F44K22
- PIC18F45K22
- PIC18F46K22
- PIC18LF23K22
- PIC18LF24K22
- PIC18LF25K22
- PIC18LF26K22
- PIC18LF43K22
- PIC18LF44K22
- PIC18LF45K22
- PIC18LF46K22

This family offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high-endurance, Flash program memory. On top of these features, the PIC18(L)F2X/4XK22 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power sensitive applications.

1.1 New Core Features

1.1.1 XLP TECHNOLOGY

All of the devices in the PIC18(L)F2X/4XK22 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- **Alternate Run Modes:** By clocking the controller from the Timer1 source or the internal oscillator block, power consumption during code execution can be reduced by as much as 90%.
- **Multiple Idle Modes:** The controller can also run with its CPU core disabled but the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operation requirements.
- **On-the-fly Mode Switching:** The power-managed modes are invoked by user code during operation, allowing the user to incorporate power-saving ideas into their application's software design.
- **Low Consumption in Key Modules:** The power requirements for both Timer1 and the Watchdog Timer are minimized. See **Section 27.0 "Electrical Specifications"** for values.

1.1.2 MULTIPLE OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC18(L)F2X/4XK22 family offer ten different oscillator options, allowing users a wide range of choices in developing application hardware. These include:

- Four Crystal modes, using crystals or ceramic resonators
- Two External Clock modes, offering the option of using two pins (oscillator input and a divide-by-4 clock output) or one pin (oscillator input, with the second pin reassigned as general I/O)
- Two External RC Oscillator modes with the same pin options as the External Clock modes
- An internal oscillator block which contains a 16 MHz HFINTOSC oscillator and a 31 kHz LFINTOSC oscillator, which together provide eight user selectable clock frequencies, from 31 kHz to 16 MHz. This option frees the two oscillator pins for use as additional general purpose I/O.
- A Phase Lock Loop (PLL) frequency multiplier, available to both external and internal oscillator modes, which allows clock speeds of up to 64 MHz. Used with the internal oscillator, the PLL gives users a complete selection of clock speeds, from 31 kHz to 64 MHz – all without using an external crystal or clock circuit.

Besides its availability as a clock source, the internal oscillator block provides a stable reference source that gives the family additional features for robust operation:

- **Fail-Safe Clock Monitor:** This option constantly monitors the main clock source against a reference signal provided by the LFINTOSC. If a clock failure occurs, the controller is switched to the internal oscillator block, allowing for continued operation or a safe application shutdown.
- **Two-Speed Start-up:** This option allows the internal oscillator to serve as the clock source from Power-on Reset, or Wake-up from Sleep mode, until the primary clock source is available.

9.4 INTCON Registers

The INTCON registers are readable and writable registers, which contain various enable, priority and flag bits.

9.5 PIR Registers

The PIR registers contain the individual flag bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are five Peripheral Interrupt Request Flag registers (PIR1, PIR2, PIR3, PIR4 and PIR5).

9.6 PIE Registers

The PIE registers contain the individual enable bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are five Peripheral Interrupt Enable registers (PIE1, PIE2, PIE3, PIE4 and PIE5). When IPEN = 0, the PEIE/GIEL bit must be set to enable any of these peripheral interrupts.

9.7 IPR Registers

The IPR registers contain the individual priority bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are five Peripheral Interrupt Priority registers (IPR1, IPR2, IPR3, IPR4 and IPR5). Using the priority bits requires that the Interrupt Priority Enable (IPEN) bit be set.

TABLE 10-5: PORTB I/O SUMMARY (CONTINUED)

Pin	Function	TRIS Setting	ANSEL Setting	Pin Type	Buffer Type	Description
RB6/KBI2/PGC	RB6	0	—	O	DIG	LATB<6> data output; not affected by analog input.
		1	—	I	TTL	PORTB<6> data input; disabled when analog input enabled.
	IOC2	1	—	I	TTL	Interrupt-on-change pin.
	TX2(3)	1	—	O	DIG	EUSART asynchronous transmit data output.
	CK2(3)	1	—	O	DIG	EUSART synchronous serial clock output.
		1	—	I	ST	EUSART synchronous serial clock input.
	PGC	x	—	I	ST	In-Circuit Debugger and ICSP™ programming clock input.
RB7/KBI3/PGD	RB7	0	—	O	DIG	LATB<7> data output; not affected by analog input.
		1	—	I	TTL	PORTB<7> data input; disabled when analog input enabled.
	IOC3	1	—	I	TTL	Interrupt-on-change pin.
	RX2(2), (3)	1	—	I	ST	EUSART asynchronous receive data input.
	DT2(2), (3)	1	—	O	DIG	EUSART synchronous serial data output.
		1	—	I	ST	EUSART synchronous serial data input.
	PGD	x	—	O	DIG	In-Circuit Debugger and ICSP™ programming data output.
		x	—	I	ST	In-Circuit Debugger and ICSP™ programming data input.

Legend: AN = Analog input or output; TTL = TTL compatible input; HV = High Voltage; OD = Open Drain; XTAL = Crystal; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C.

Note 1: Default pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

3: Function on PORTD and PORTE for PIC18(L)F4XK22 devices.

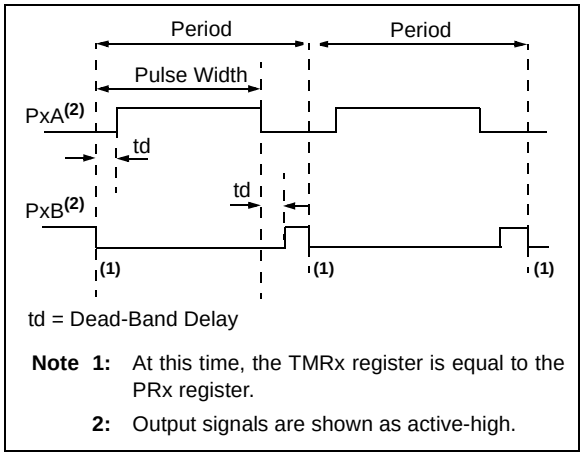
14.4.1 HALF-BRIDGE MODE

In Half-Bridge mode, two pins are used as outputs to drive push-pull loads. The PWM output signal is output on the CCPx/PxA pin, while the complementary PWM output signal is output on the PxB pin (see Figure 14-9). This mode can be used for half-bridge applications, as shown in Figure 14-9, or for full-bridge applications, where four power switches are being modulated with two PWM signals.

In Half-Bridge mode, the programmable dead-band delay can be used to prevent shoot-through current in half-bridge power devices. The value of the PDC<6:0> bits of the PWMxCON register sets the number of instruction cycles before the output is driven active. If the value is greater than the duty cycle, the corresponding output remains inactive during the entire cycle. See **Section 14.4.5 "Programmable Dead-Band Delay Mode"** for more details of the dead-band delay operations.

Since the PxA and PxB outputs are multiplexed with the PORT data latches, the associated TRIS bits must be cleared to configure PxA and PxB as outputs.

FIGURE 14-8: EXAMPLE OF HALF-BRIDGE PWM OUTPUT

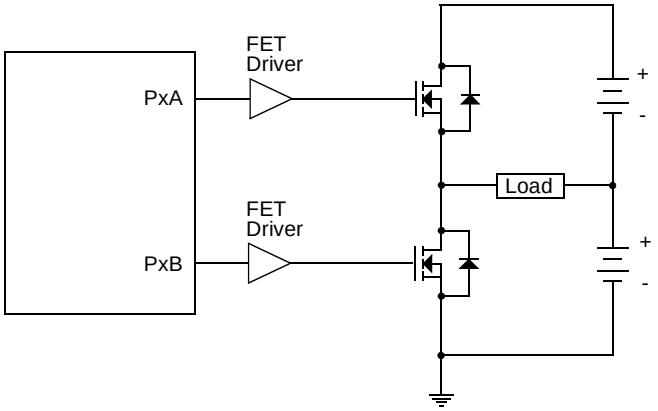


Note 1: At this time, the TMRx register is equal to the PRx register.

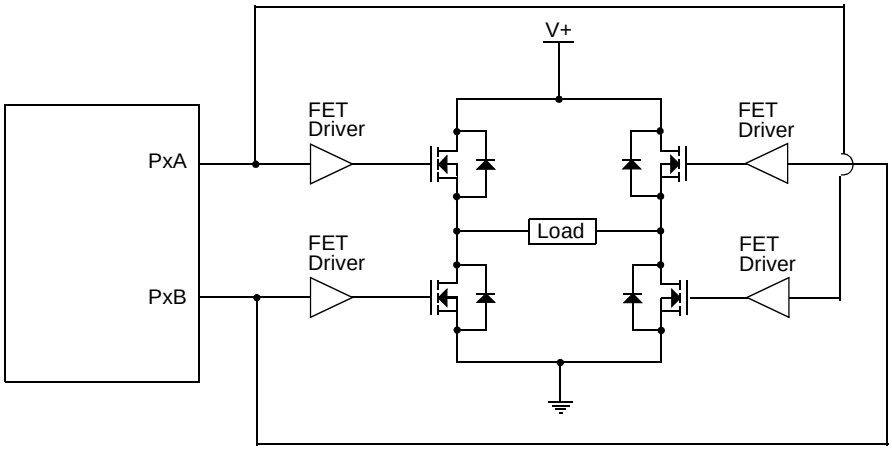
2: Output signals are shown as active-high.

FIGURE 14-9: EXAMPLE OF HALF-BRIDGE APPLICATIONS

Standard Half-Bridge Circuit ("Push-Pull")



Half-Bridge Output Driving a Full-Bridge Circuit



14.4.2 FULL-BRIDGE MODE

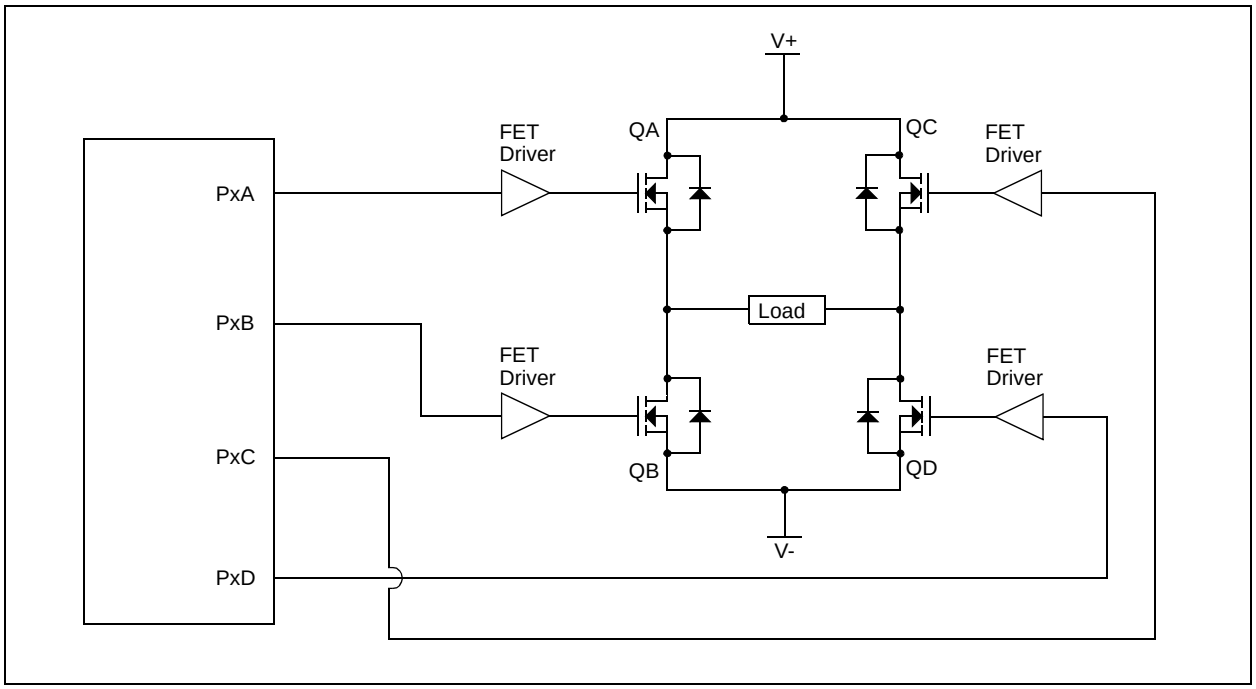
In Full-Bridge mode, all four pins are used as outputs. An example of full-bridge application is shown in Figure 14-10.

In the Forward mode, pin CCPx/PxA is driven to its active state, pin PxD is modulated, while PxB and PxC will be driven to their inactive state as shown in Figure 14-11.

In the Reverse mode, PxC is driven to its active state, pin PxB is modulated, while PxA and PxD will be driven to their inactive state as shown Figure 14-11.

PxA, PxB, PxC and PxD outputs are multiplexed with the PORT data latches. The associated TRIS bits must be cleared to configure the PxA, PxB, PxC and PxD pins as outputs.

FIGURE 14-10: EXAMPLE OF FULL-BRIDGE APPLICATION



15.4 I²C Mode Operation

All MSSPx I²C communication is byte oriented and shifted out MSb first. Six SFR registers and 2 interrupt flags interface the module with the PIC microcontroller and user software. Two pins, SDAx and SCLx, are exercised by the module to communicate with other external I²C devices.

15.4.1 BYTE FORMAT

All communication in I²C is done in 9-bit segments. A byte is sent from a master to a slave or vice-versa, followed by an Acknowledge bit sent back. After the 8th falling edge of the SCLx line, the device outputting data on the SDAx changes that pin to an input and reads in an acknowledge value on the next clock pulse.

The clock signal, SCLx, is provided by the master. Data is valid to change while the SCLx signal is low, and sampled on the rising edge of the clock. Changes on the SDAx line while the SCLx line is high define special conditions on the bus, explained below.

15.4.2 DEFINITION OF I²C TERMINOLOGY

There is language and terminology in the description of I²C communication that have definitions specific to I²C. That word usage is defined below and may be used in the rest of this document without explanation. This table was adapted from the Phillips I²C specification.

15.4.3 SDAx AND SCLx PINS

Selection of any I²C mode with the SSPxEN bit set, forces the SCLx and SDAx pins to be open-drain. These pins should be set by the user to inputs by setting the appropriate TRIS bits.

Note:	Data is tied to output zero when an I²C mode is enabled.

15.4.4 SDAx HOLD TIME

The hold time of the SDAx pin is selected by the SDAHT bit of the SSPxCON3 register. Hold time is the time SDAx is held valid after the falling edge of SCLx. Setting the SDAHT bit selects a longer 300 ns minimum hold time and may help on buses with large capacitance.

TABLE 15-1: I²C BUS TERMS

TERM	Description
Transmitter	The device which shifts data out onto the bus.
Receiver	The device which shifts data in from the bus.
Master	The device that initiates a transfer, generates clock signals and terminates a transfer.
Slave	The device addressed by the master.
Multi-master	A bus with more than one device that can initiate data transfers.
Arbitration	Procedure to ensure that only one master at a time controls the bus. Winning arbitration ensures that the message is not corrupted.
Synchronization	Procedure to synchronize the clocks of two or more devices on the bus.
Idle	No master is controlling the bus, and both SDAx and SCLx lines are high.
Active	Any time one or more master devices are controlling the bus.
Addressed Slave	Slave device that has received a matching address and is actively being clocked by a master.
Matching Address	Address byte that is clocked into a slave that matches the value stored in SSPxADD.
Write Request	Slave receives a matching address with R/$\overline{W}$ bit clear, and is ready to clock in data.
Read Request	Master sends an address byte with the R/$\overline{W}$ bit set, indicating that it wishes to clock data out of the Slave. This data is the next and all following bytes until a Restart or Stop.
Clock Stretching	When a device on the bus holds SCLx low to stall communication.
Bus Collision	Any time the SDAx line is sampled low by the module while it is outputting and expected high state.

15.6.5 I²C MASTER MODE REPEATED START CONDITION TIMING

A Repeated Start condition (Figure 15-27) occurs when the RSEN bit of the SSPxCON2 register is programmed high and the master state machine is no longer active. When the RSEN bit is set, the SCLx pin is asserted low. When the SCLx pin is sampled low, the Baud Rate Generator is loaded and begins counting. The SDAx pin is released (brought high) for one Baud Rate Generator count (TBRG). When the Baud Rate Generator times out, if SDAx is sampled high, the SCLx pin will be deasserted (brought high). When SCLx is sampled high, the Baud Rate Generator is reloaded and begins counting. SDAx and SCLx must be sampled high for one TBRG. This action is then followed by assertion of the SDAx pin (SDAx = 0) for one TBRG while SCLx is high. SCLx is asserted low.

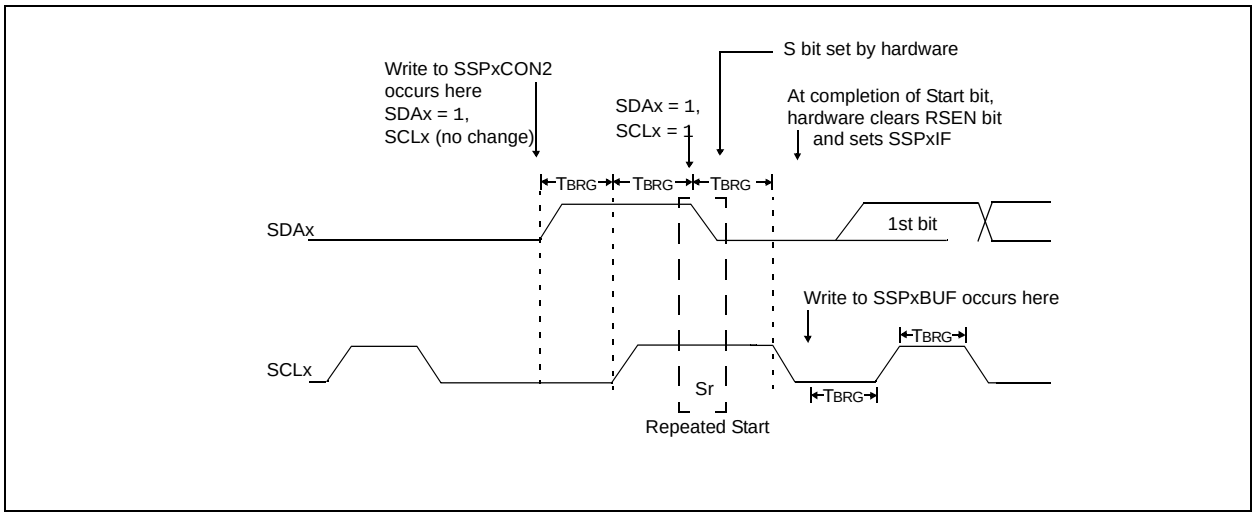
Following this, the RSEN bit of the SSPxCON2 register will be automatically cleared and the Baud Rate Generator will not be reloaded, leaving the SDAx pin held low. As soon as a Start condition is detected on the SDAx and SCLx pins, the S bit of the SSPxSTAT register will be set. The SSPxIF bit will not be set until the Baud Rate Generator has timed out.

Note 1: If RSEN is programmed while any other event is in progress, it will not take effect.

2: A bus collision during the Repeated Start condition occurs if:

- SDAx is sampled low when SCLx goes from low-to-high.
- SCLx goes low before SDAx is asserted low. This may indicate that another master is attempting to transmit a data '1'.

FIGURE 15-27: REPEAT START CONDITION WAVEFORM



REGISTER 15-3: SSPxCON1: SSPx CONTROL REGISTER 1 (CONTINUED)

bit 3-0 **SSPxM<3:0>:** Synchronous Serial Port Mode Select bits
0000 = SPI Master mode, clock = FOSC/4
0001 = SPI Master mode, clock = FOSC/16
0010 = SPI Master mode, clock = FOSC/64
0011 = SPI Master mode, clock = TMR2 output/2
0100 = SPI Slave mode, clock = SCKx pin, $\overline{SSx}$ pin control enabled
0101 = SPI Slave mode, clock = SCKx pin, $\overline{SSx}$ pin control disabled, $\overline{SSx}$ can be used as I/O pin
0110 = I^2C Slave mode, 7-bit address
0111 = I^2C Slave mode, 10-bit address
1000 = I^2C Master mode, clock = FOSC / (4 * (SSPxADD+1))**(4)**
1001 = Reserved
1010 = SPI Master mode, clock = FOSC/(4 * (SSPxADD+1))
1011 = I^2C firmware controlled Master mode (slave idle)
1100 = Reserved
1101 = Reserved
1110 = I^2C Slave mode, 7-bit address with Start and Stop bit interrupts enabled
1111 = I^2C Slave mode, 10-bit address with Start and Stop bit interrupts enabled

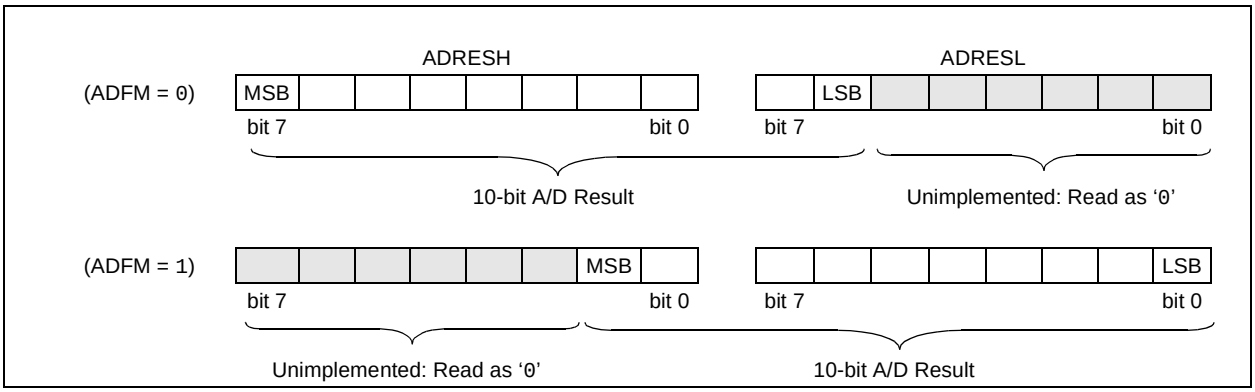
Note 1: In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPxBUF register.
2: When enabled, these pins must be properly configured as input or output.
3: When enabled, the SDAx and SCLx pins must be configured as inputs.
4: SSPxADD values of 0, 1 or 2 are not supported for I^2C mode.

17.1.7 RESULT FORMATTING

The 10-bit A/D conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON2 register controls the output format.

Figure 17-2 shows the two output formats.

FIGURE 17-2: 10-BIT A/D CONVERSION RESULT FORMAT



18.5 Operation During Sleep

The comparator, if enabled before entering Sleep mode, remains active during Sleep. The additional current consumed by the comparator is shown separately in **Section 27.0 "Electrical Specifications"**. If the comparator is not used to wake the device, power consumption can be minimized while in Sleep mode by turning off the comparator. Each comparator is turned off by clearing the CxON bit of the CMxCON0 register.

A change to the comparator output can wake-up the device from Sleep. To enable the comparator to wake the device from Sleep, the CxIE bit of the PIE2 register and the PEIE/GIEL bit of the INTCON register must be set. The instruction following the SLEEP instruction always executes following a wake from Sleep. If the GIE/GIEH bit of the INTCON register is also set, the device will then execute the Interrupt Service Routine.

18.6 Effects of a Reset

A device Reset forces the CMxCON0 and CM2CON1 registers to their Reset states. This forces both comparators and the voltage references to their Off states.Comparator Control Registers.

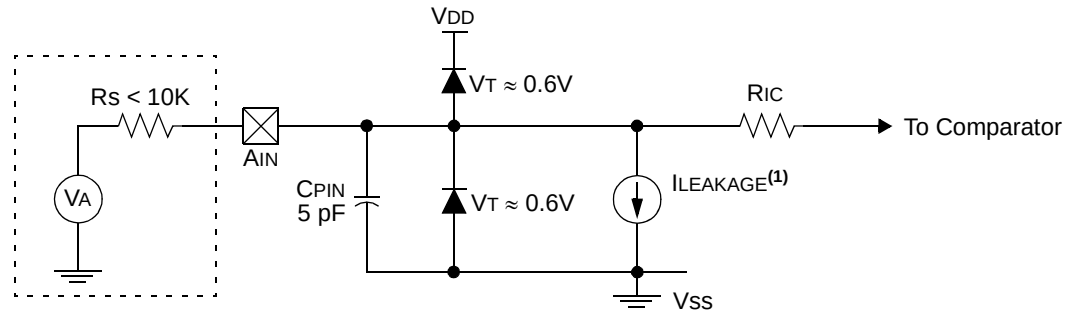
18.7 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 18-5. Since the analog input pins share their connection with a digital input, they have reverse biased ESD protection diodes to V_{DD} and V_{SS}. The analog input, therefore, must be between V_{SS} and V_{DD}. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur.

A maximum source impedance of 10 kΩ is recommended for the analog sources. Also, any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current to minimize inaccuracies introduced.

Note 1:	When reading a PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert as an analog input, according to the input specification.
2:	Analog levels on any pin defined as a digital input, may cause the input buffer to consume more current than is specified.

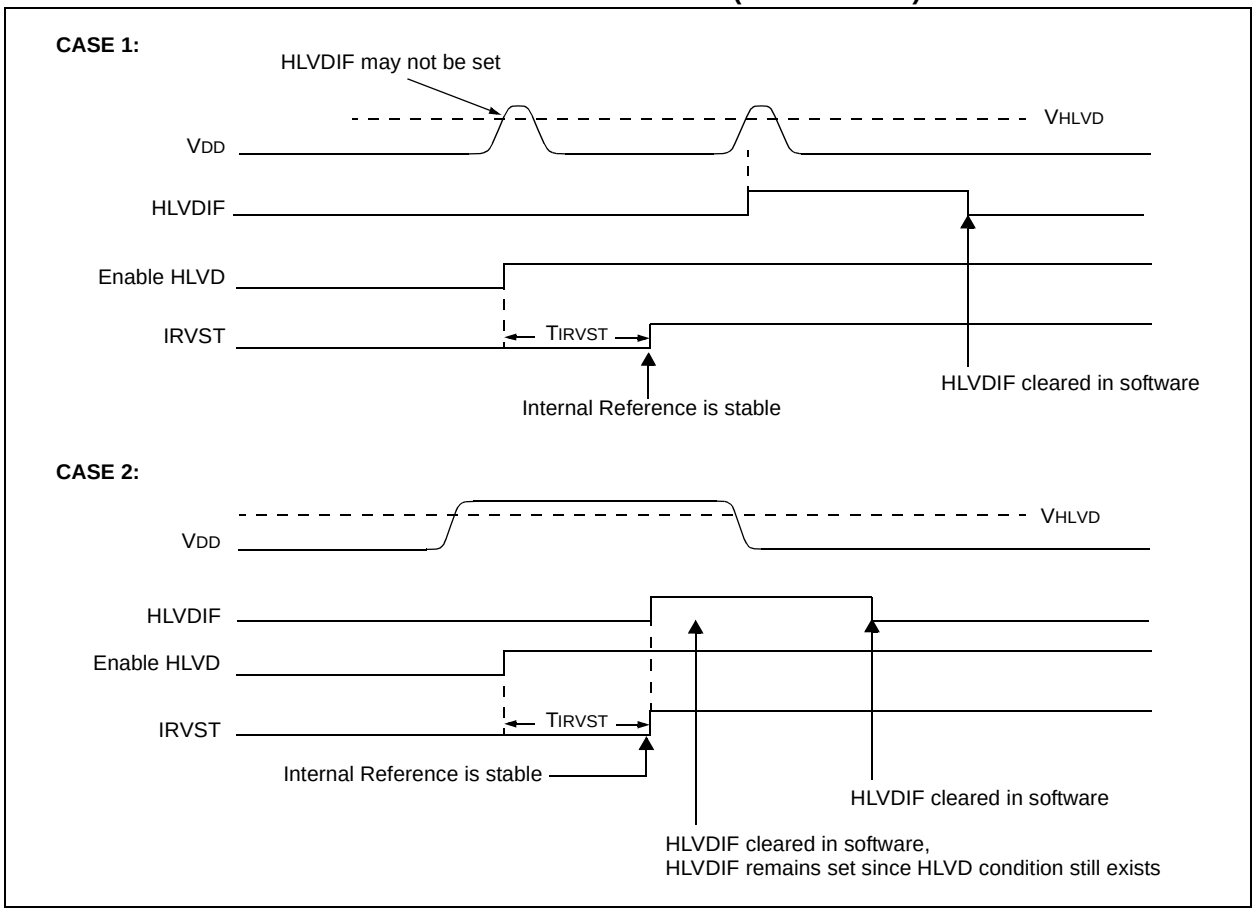
FIGURE 18-5: ANALOG INPUT MODEL



Legend: C_{PIN} = Input Capacitance
$I_{LEAKAGE}$ = Leakage Current at the pin due to various junctions
R_{IC} = Interconnect Resistance
R_S = Source Impedance
V_A = Analog Voltage
V_T = Threshold Voltage

Note 1: See **Section 27.0 "Electrical Specifications"**.

FIGURE 23-3: HIGH-VOLTAGE DETECT OPERATION (VDIRMAG = 1)

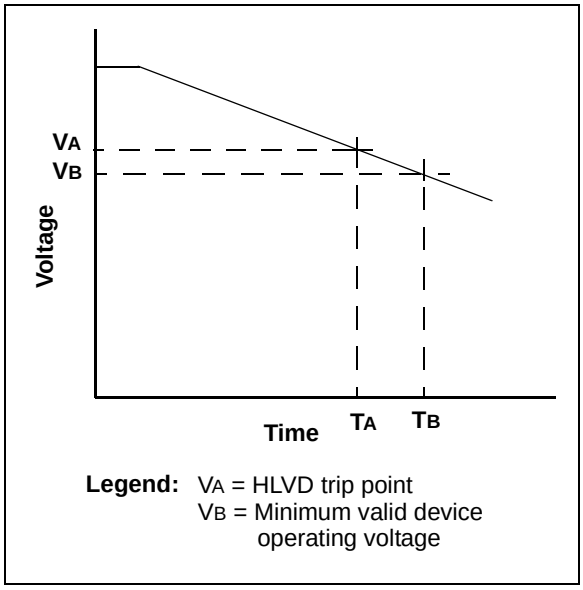


23.6 Applications

In many applications, it is desirable to detect a drop below, or rise above, a particular voltage threshold. For example, the HLVD module could be periodically enabled to detect Universal Serial Bus (USB) attach or detach. This assumes the device is powered by a lower voltage source than the USB when detached. An attach would indicate a high-voltage detect from, for example, 3.3V to 5V (the voltage on USB) and vice versa for a detach. This feature could save a design a few extra components and an attach signal (input pin).

For general battery applications, Figure 23-4 shows a possible voltage curve. Over time, the device voltage decreases. When the device voltage reaches voltage VA, the HLVD logic generates an interrupt at time, TA. The interrupt could cause the execution of an ISR, which would allow the application to perform "house-keeping tasks" and a controlled shutdown before the device voltage exits the valid operating range at TB. This would give the application a time window, represented by the difference between TA and TB, to safely exit.

FIGURE 23-4: TYPICAL LOW-VOLTAGE DETECT APPLICATION



COMF **Complement f**

Syntax: COMF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $(\bar{f}) \rightarrow$ dest

Status Affected: N, Z

Encoding:

0001	11da	ffff	ffff

Description: The contents of register 'f' are complemented. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `COMF REG, 0, 0`

Before Instruction
REG = 13h
After Instruction
REG = 13h
W = ECh

CPFSEQ **Compare f with W, skip if f = W**

Syntax: CPFSEQ f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) = (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	001a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of W by performing an unsigned subtraction.
If 'f' = W, then the fetched instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    CPFSEQ REG, 0
NEQUAL  :
EQUAL   :
```

Before Instruction
PC Address = HERE
W = ?
REG = ?
After Instruction
If REG = W;
PC = Address (EQUAL)
If REG ≠ W;
PC = Address (NEQUAL)

25.2 Extended Instruction Set

In addition to the standard 75 instructions of the PIC18 instruction set, PIC18(L)F2X/4XK22 devices also provide an optional extension to the core CPU functionality. The added features include eight additional instructions that augment indirect and indexed addressing operations and the implementation of Indexed Literal Offset Addressing mode for many of the standard PIC18 instructions.

The additional features of the extended instruction set are disabled by default. To enable them, users must set the XINST Configuration bit.

The instructions in the extended set can all be classified as literal operations, which either manipulate the File Select Registers, or use them for indexed addressing. Two of the instructions, ADDFSR and SUBFSR, each have an additional special instantiation for using FSR2. These versions (ADDULNK and SUBULNK) allow for automatic return after execution.

The extended instructions are specifically implemented to optimize re-entrant program code (that is, code that is recursive or that uses a software stack) written in high-level languages, particularly C. Among other things, they allow users working in high-level languages to perform certain operations on data structures more efficiently. These include:

- dynamic allocation and deallocation of software stack space when entering and leaving subroutines
- function pointer invocation
- software Stack Pointer manipulation
- manipulation of variables located in a software stack

A summary of the instructions in the extended instruction set is provided in Table 25-3. Detailed descriptions are provided in **Section 25.2.2 "Extended Instruction Set"**. The opcode field descriptions in Table 25-1 apply to both the standard and extended PIC18 instruction sets.

Note:	The instruction set extension and the Indexed Literal Offset Addressing mode were designed for optimizing applications written in C; the user may likely never use these instructions directly in assembler. The syntax for these commands is provided as a reference for users who may be reviewing code that has been generated by a compiler.

25.2.1 EXTENDED INSTRUCTION SYNTAX

Most of the extended instructions use indexed arguments, using one of the File Select Registers and some offset to specify a source or destination register. When an argument for an instruction serves as part of indexed addressing, it is enclosed in square brackets (“[ ]”). This is done to indicate that the argument is used as an index or offset. MPASM™ Assembler will flag an error if it determines that an index or offset value is not bracketed.

When the extended instruction set is enabled, brackets are also used to indicate index arguments in byte-oriented and bit-oriented instructions. This is in addition to other changes in their syntax. For more details, see **Section 25.2.3.1 “Extended Instruction Syntax with Standard PIC18 Commands”**.

Note:	In the past, square brackets have been used to denote optional arguments in the PIC18 and earlier instruction sets. In this text and going forward, optional arguments are denoted by braces (“{ }”).

TABLE 25-3: EXTENSIONS TO THE PIC18 INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	16-Bit Instruction Word				Status Affected
				MSb			LSb	
ADDFSR	f, k	Add literal to FSR	1	1110	1000	ffkk	kkkk	None
ADDULNK	k	Add literal to FSR2 and return	2	1110	1000	11kk	kkkk	None
CALLW		Call subroutine using WREG	2	0000	0000	0001	0100	None
MOVSF	z_s, f_d	Move z_s (source) to 1st word	2	1110	1011	0zzz	zzzz	None
		f_d (destination) 2nd word		1111	ffff	ffff	ffff	
MOVSS	z_s, z_d	Move z_s (source) to 1st word	2	1110	1011	1zzz	zzzz	None
		z_d (destination) 2nd word		1111	xxxx	xzzz	zzzz	
PUSHL	k	Store literal at FSR2, decrement FSR2	1	1110	1010	kkkk	kkkk	None
SUBFSR	f, k	Subtract literal from FSR	1	1110	1001	ffkk	kkkk	None
SUBULNK	k	Subtract literal from FSR2 and return	2	1110	1001	11kk	kkkk	None

27.8 DC Characteristics: Input/Output Characteristics, PIC18(L)F2X/4XK22 (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D159	VOL	**Output Low Voltage** I/O ports	—	—	0.6	V	IOL = 8 mA, VDD = 5V IOL = 6 mA, VDD = 3.3V IOL = 1.8 mA, VDD = 1.8V
D161	VOH	**Output High Voltage(3)** I/O ports	VDD - 0.7	—	—	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 1 mA, VDD = 1.8V

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Parameter is characterized but not tested.

TABLE 27-22: A/D CONVERSION REQUIREMENTS PIC18(L)F2X/4XK22

Standard Operating Conditions (unless otherwise stated) Operating temperature Tested at +25°C							
Param. No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
130	TAD	A/D Clock Period	1	—	25	µs	-40°C to +85°C
			1	—	4	µs	+85°C to +125°C
131	TCNV	Conversion Time (not including acquisition time) **(Note 1)**	11	—	11	TAD	
132	TACQ	Acquisition Time **(Note 2)**	1.4	—	—	µs	VDD = 3V, Rs = 50Ω
135	TSWC	Switching Time from Convert → Sample	—	—	**(Note 3)**		
136	TDIS	Discharge Time	1	—	1	TCY	

Note 1: ADRES register may be read on the following TCY cycle.

2: The time for the holding capacitor to acquire the "New" input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD). The source impedance (*RS*) on the input channels is 50 Ω.

3: On the following cycle of the device clock.

FIGURE 28-5: PIC18LF2X/4XK22 DELTA IPD BROWN-OUT RESET (BOR)

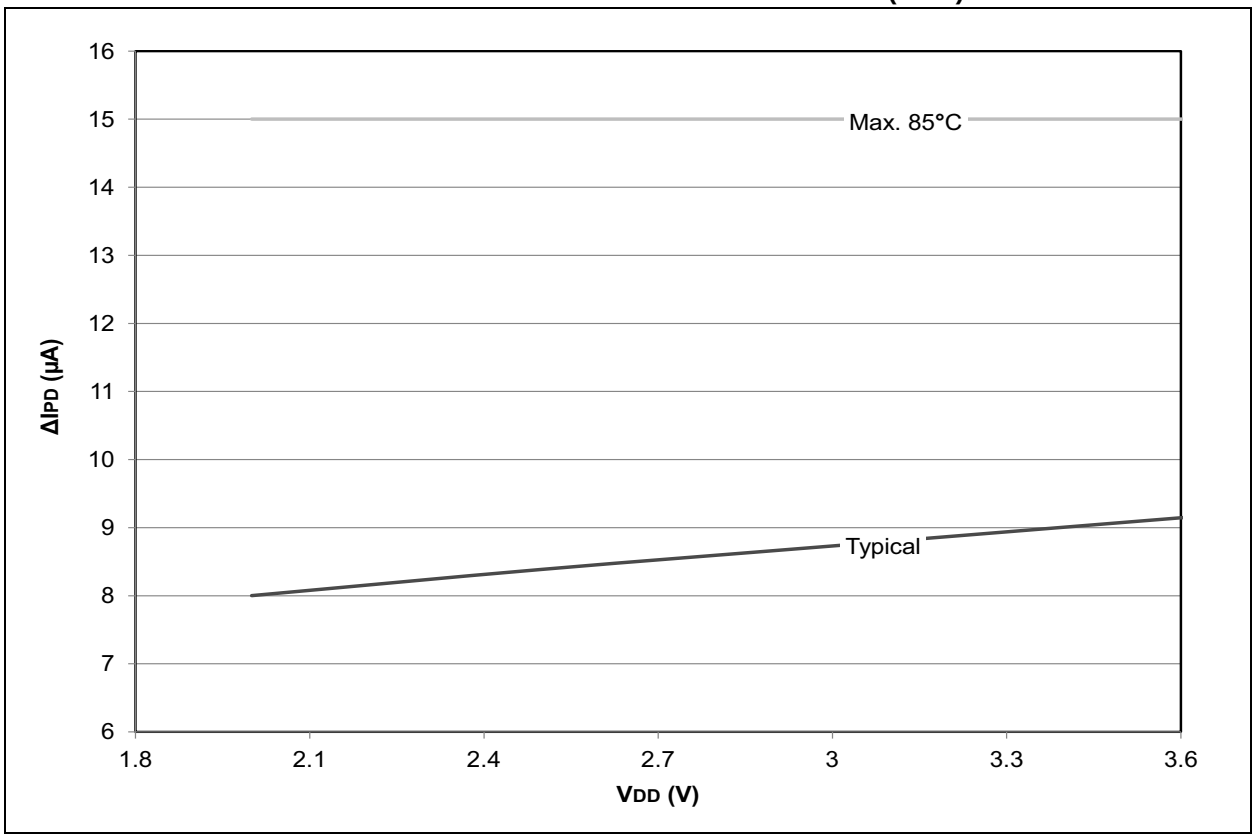


FIGURE 28-6: PIC18F2X/4XK22 DELTA IPD BROWN-OUT RESET (BOR)

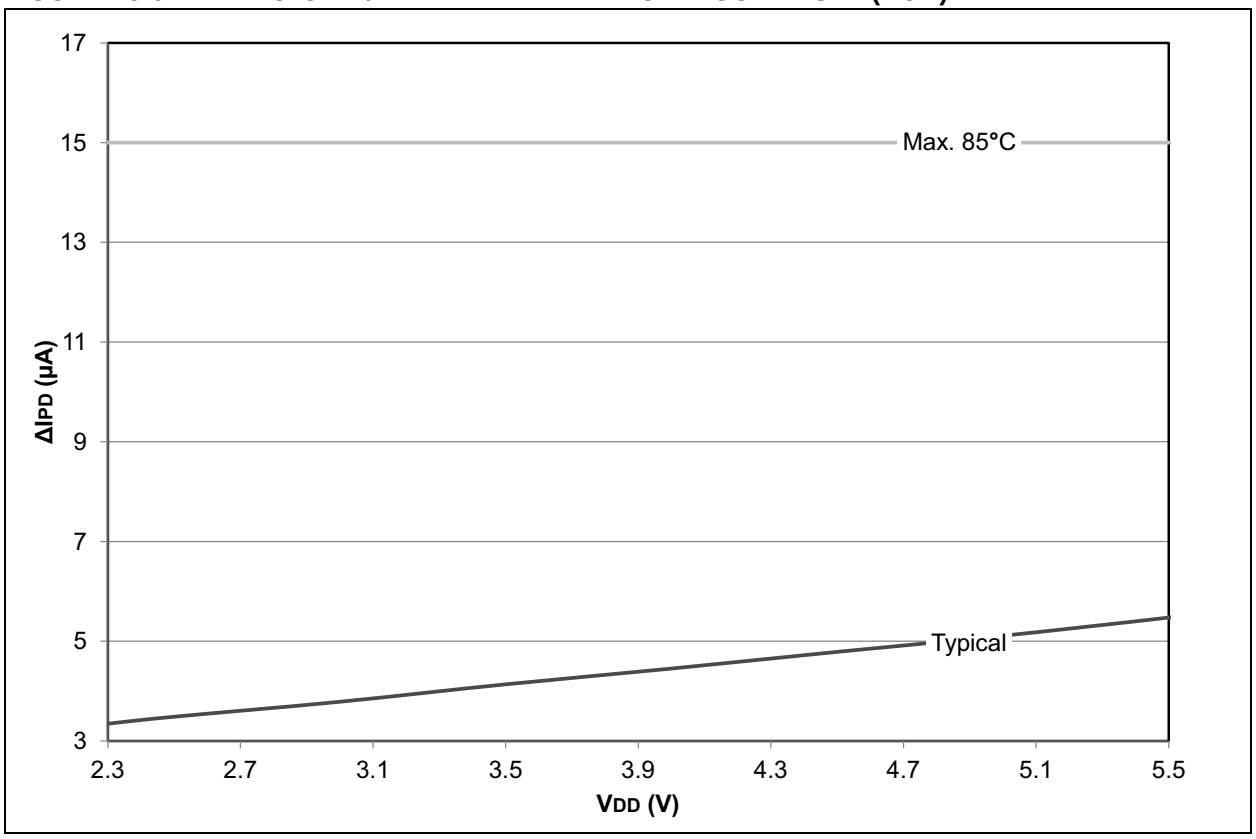


FIGURE 28-36: PIC18F2X/4XK22 TYPICAL IDD: RC_IDLE LF-INTOSC 31 kHz

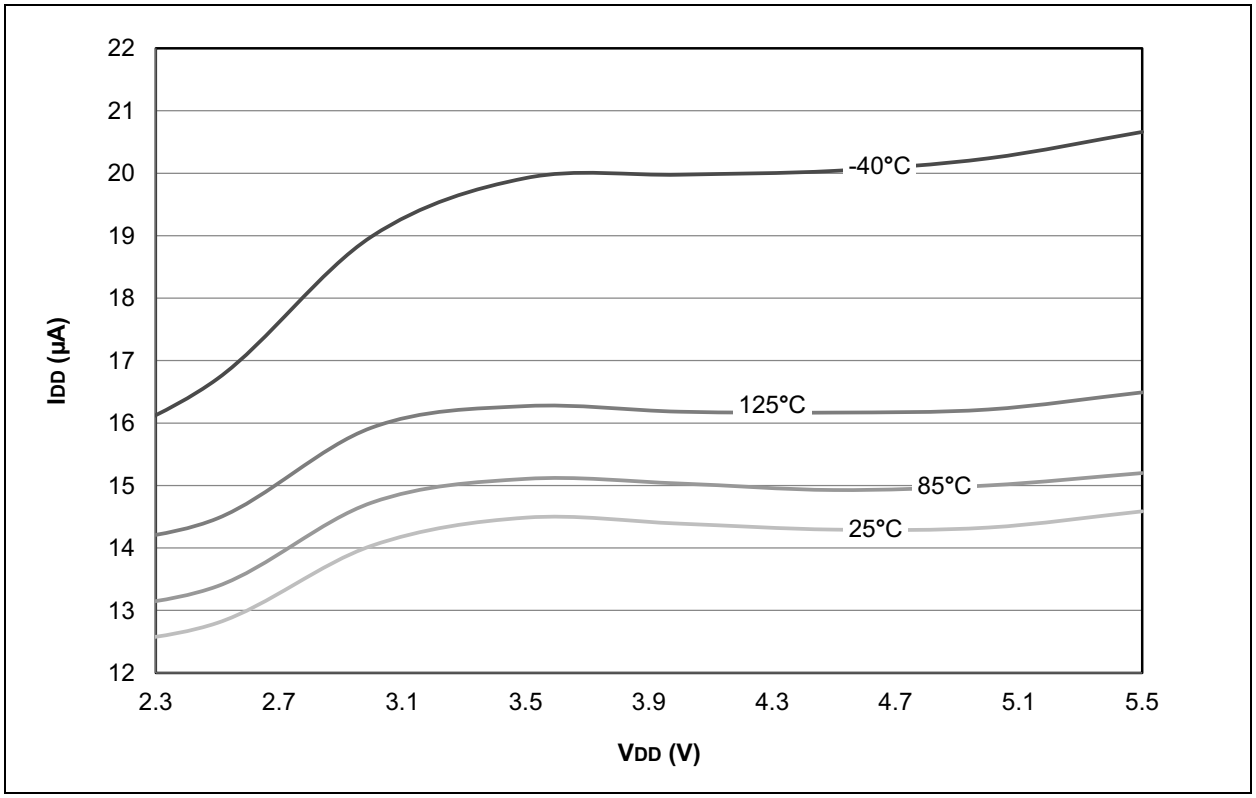


FIGURE 28-37: PIC18F2X/4XK22 MAXIMUM IDD: RC_IDLE LF-INTOSC 31 kHz

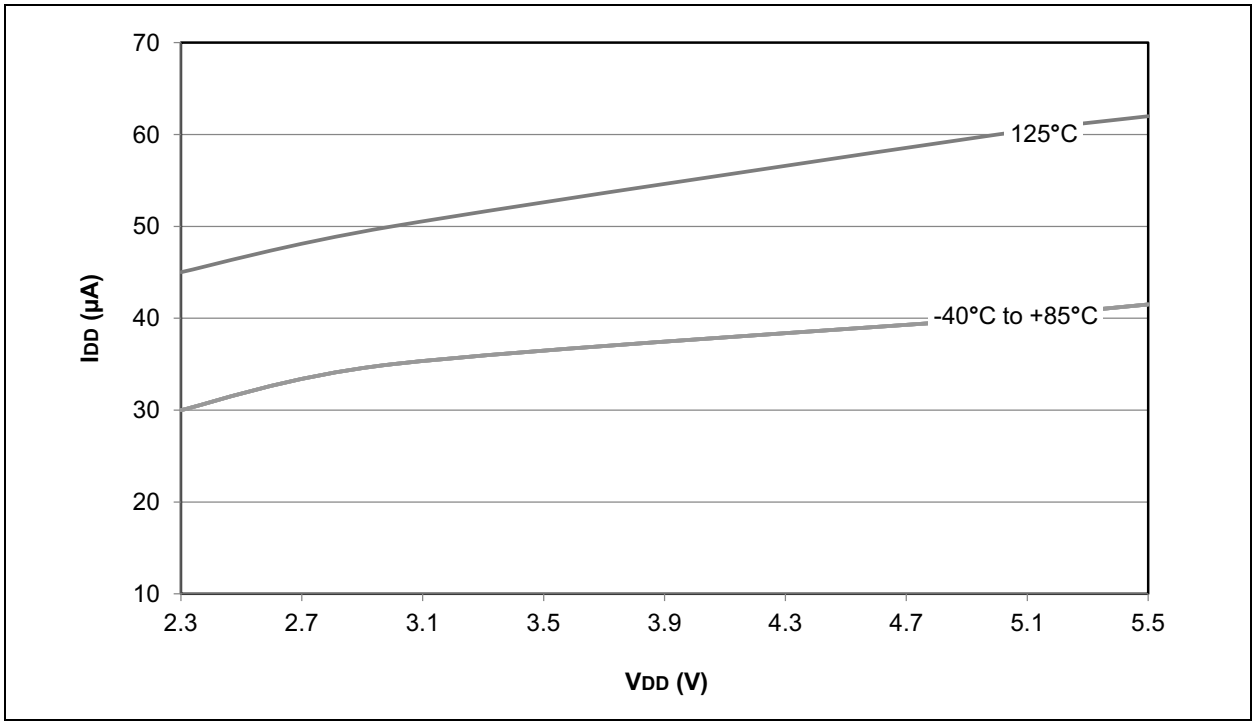
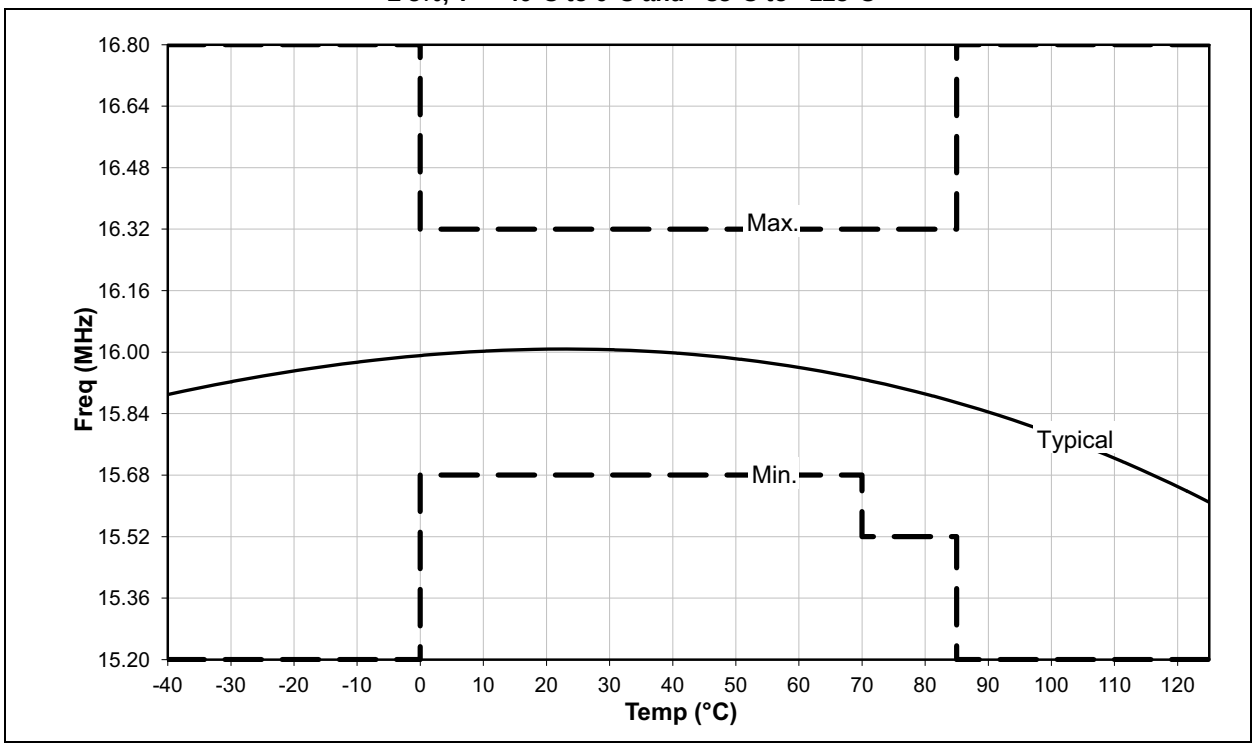
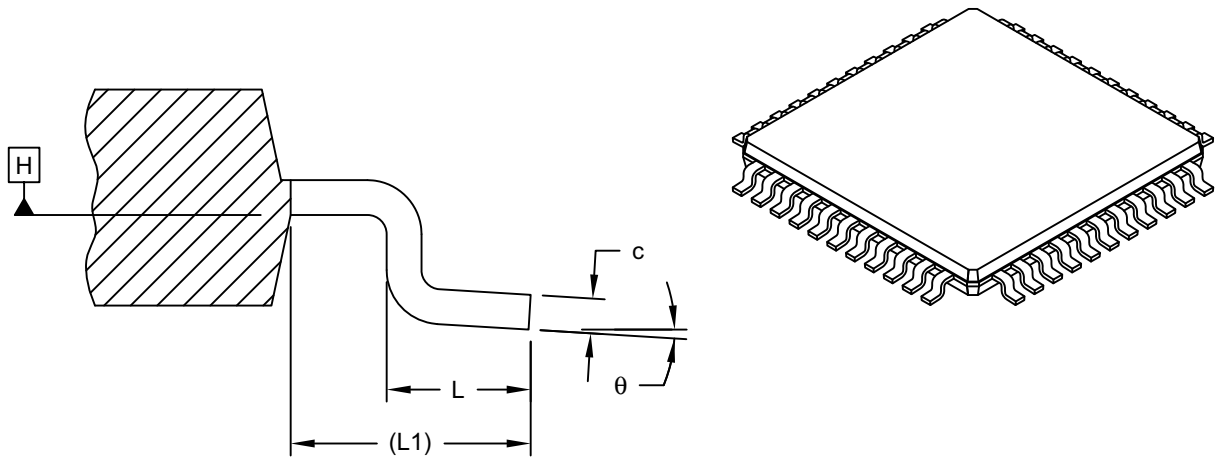


FIGURE 28-100: PIC18(L)F2X/4XK22 HF-INTOSC FREQUENCY vs. TEMPERATURE at 16 MHz
MIN / MAX: ± 2%, T = 0°C to +70°C
+2% / -3%, T = +70°C to +85°C
± 5%, T = -40°C to 0°C and +85°C to +125°C



44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	-	-	1.20
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Width	E		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Width	b	0.30	0.37	0.45
Lead Thickness	c	0.09	-	0.20
Lead Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	θ	0°	3.5°	7°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Exact shape of each corner is optional.
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076C Sheet 2 of 2